

Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

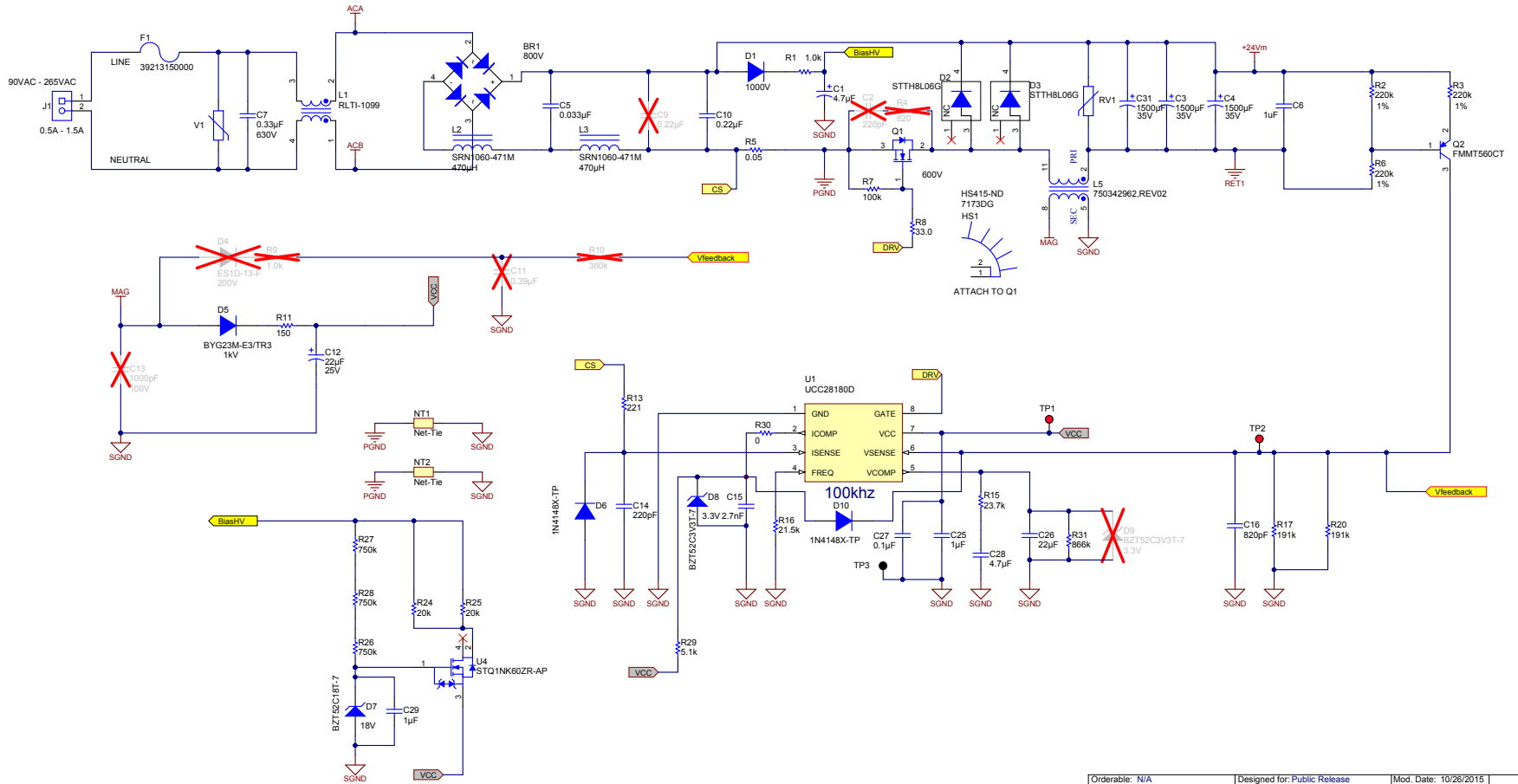
Cannot open file C:\Users\ao132468\Downloads\Pictur3.jpg

Orderable: N/A	Designed for: Public Release	Mod. Date: 10/26/2015
TID #: ChangeMe!	Project Title: BLDC ceiling fan with buck PFC	
Number: TIDA-00652	Rev: E3	Sheet Title:
SVN Rev.: Not in version control	Assembly Variant: 001	Sheet: 1 of 4
Drawn By:	File: CoverSheet_SCHDoc	Size: B
Engineer: Krishna Dora	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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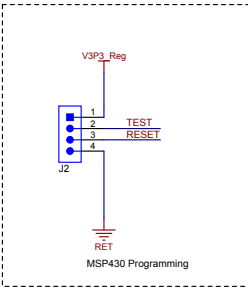
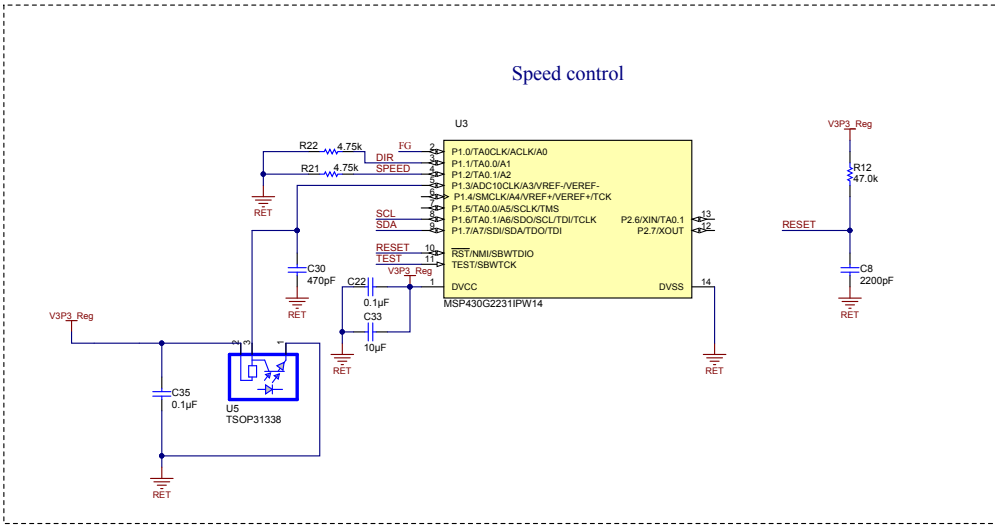
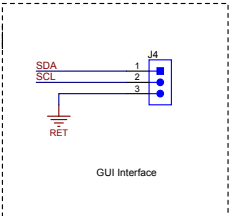
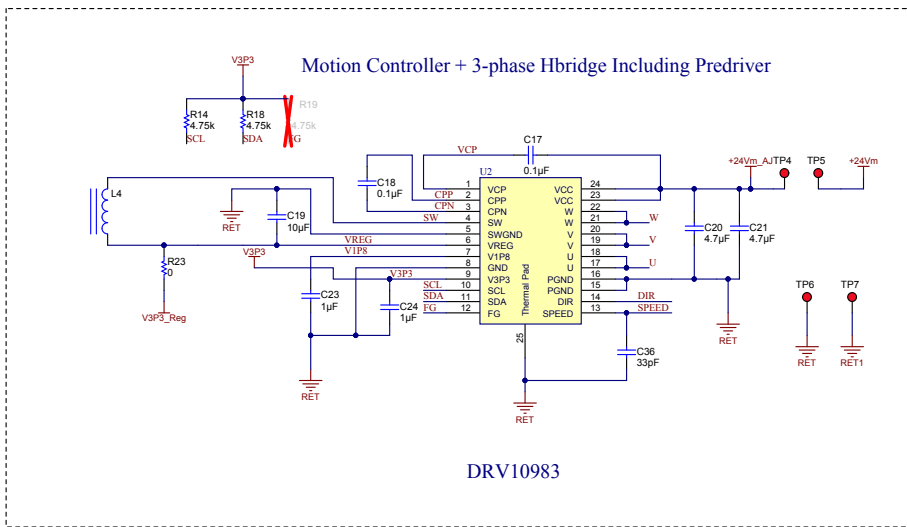


TIDA-00652



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TID #: ChangeMe!	Project Title: BLDC ceiling fan with buck PFC	
Number: TIDA-00652	Rev: E3	Sheet Title:
SVN Rev.: Not in version control	Assembly Variant: 001	Sheet 2 of 4
Drawn By:	File: Sheet1_SchDoc	Size: B
Engineer: Krishna Dora	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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TID #: ChangeMe!	Number: TIDA-00652	Rev: E3
SVN Rev.: Not in version control	Assembly Variant: 001	Sheet: 3 of 4
Drawn By: Engineer: Krishna Dora	File: Sheet2_SchDoc	Size: B
Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		<a href="http://www.ti.com">http://www.ti.com</a>



PCB Number: TIDA-00652  
PCB Rev: E3

PCB  
LOGO  
Texas Instruments

LBL1  
PCB Label  
Size: 0.65" x 0.20"

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

You should delete the nylon screws/standoffs and/or the bump-ons as needed for your design (or substitute other parts from Hardware.IntLib). Bump-ons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

**222**  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

**223**  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

**224**  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: TIDA-00652	Rev: E3	Sheet Title:
SVN Rev.: Not in version control	Assembly Variant: 001	Sheet: 4 of 4
Drawn By:	File: TID_Hardware_SchDoc	Size: B
Engineer: Krishna Dora	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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